

## BOARD'S DRILL SCHEDULE

DRILL SYMBOL	DRILL SIZE	COUNT	PLATED	Tolerance	COMMENT
	.00795	841	YES		
	. 05	100	YES		
0	. 12	4	YES		

## Board Characteristics

- O. Material RF775
- 1. All dimensions in mm, unless specified
- 2. Minimum trace width: 4 mils
- 3. 0.5 Oz Copper on all layers
- 4. Silkscreen on Component Side.
- 5. Polyimide Coverlay (Kapton Soldermask) on Top and Bottom, as per Gerbers
- 6. Soft Au finish (ENIG) for Al wire bonding and hand soldering on all pads.
- 7. Place two Stiffeners on Top (Component) side of Flex PCB.
- 7.1. Stiffener Dimensions and position as shown.
- 8. Total flex circuit thickness cannot exceed 0.012", not including stiffener

## Layer Order 5-Layer Flex PCB

Film 1 - Component Side

Film 2 - Signal 2

Film 3 - Power

Film 4 - Signal 3

Film 5 - Bottom

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES	CONTRACT NO.		UNIVERSITY OF CHICAGO ELECTRONICS DEVELOPMENT GROUP			
. X X . X X X D O N O T S C A L E D R A W I N G	APPROVALS	DATE	111 1Kx6K CCD Flex Extension			
TREATMENT			Specification Drawing			
FINISH	CHECKED M. Bogdan	3/7/2021	CI7E ECAM NA DEV			
SIMILAR TO ACT. WT CALC WT	ISSUED		B 130 NO. NO. 2947—C			